

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
^[C] Molding shrinkage, parallel	0.3 / *	%	ISO 294-4, 2577
^[C] Molding shrinkage, normal	0.8 / *	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	10000 / 6000	MPa	ISO 527
^[C] Stress at break	180 / 115	MPa	ISO 527
^[C] Strain at break	3.2 / 6.5	%	ISO 527
Flexural modulus, 23°C	8500 / 5100	MPa	ISO 178
Flexural strength	250 / 160	MPa	ISO 178
^[C] Charpy impact strength, +23°C	75 / 90	kJ/m ²	ISO 179/1eU
^[C] Charpy impact strength, -30°C	60 / -	kJ/m ²	ISO 179/1eU
^[C] Charpy notched impact strength, +23°C	10 / 18	kJ/m ²	ISO 179/1eA
^[C] Charpy notched impact strength, -30°C	8 / -	kJ/m ²	ISO 179/1eA

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Melting temperature, 10°C/min	222 / *	°C	ISO 11357-1/-3
^[C] Temp. of deflection under load, 1.80 MPa	208 / *	°C	ISO 75-1/-2
^[C] Temp. of deflection under load, 0.45 MPa	218 / *	°C	ISO 75-1/-2
^[C] Burning Behav. at thickness h	HB / *	class	IEC 60695-11-10
Thickness tested	0.4 / *	mm	-
Yellow Card available	yes / *	-	-

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Volume resistivity	1E13 / -	Ohm*m	IEC 62631-3-1
^[C] Surface resistivity	* / 1E12	Ohm	IEC 62631-3-2
^[C] Comparative tracking index	400 / -	-	IEC 60112

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
^[C] Density	1360 / -	kg/m ³	ISO 1183

[C]: CAMPUS

Characteristics

Processing

Injection Molding

Special Characteristics

Heat stabilized or stable to heat

Delivery form

Black

Applications

Automotive, Electrical and Electronical